



FIG. 1

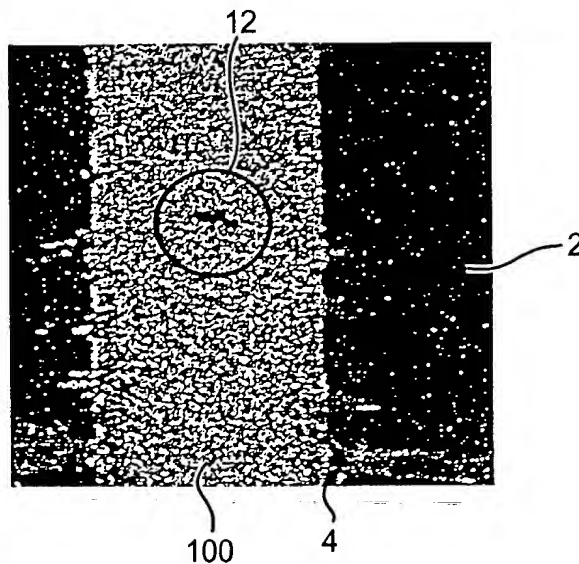


FIG. 2

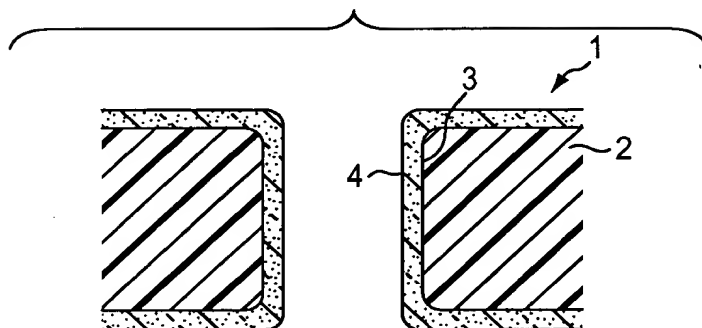


FIG. 3

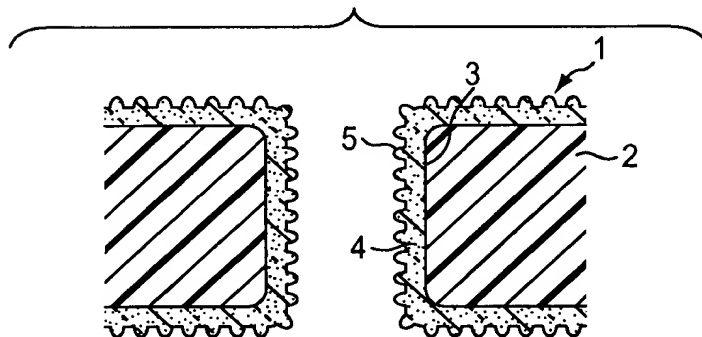




FIG. 4

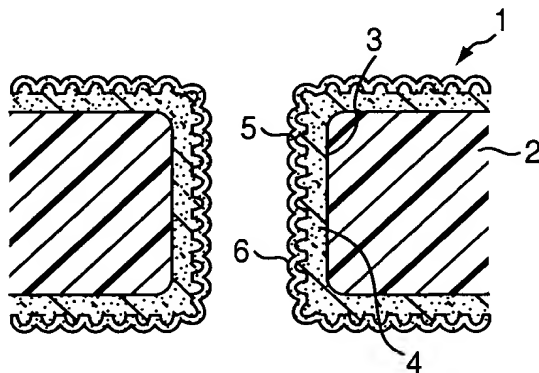


FIG. 5

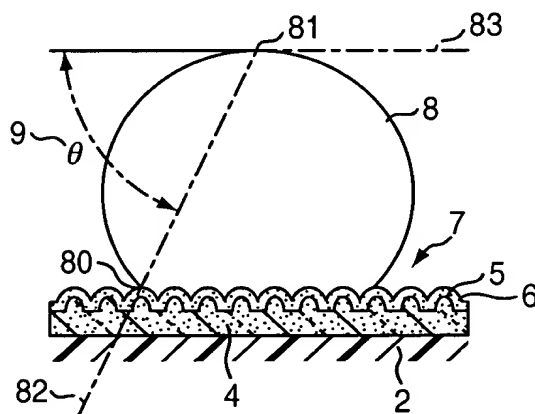


FIG. 6

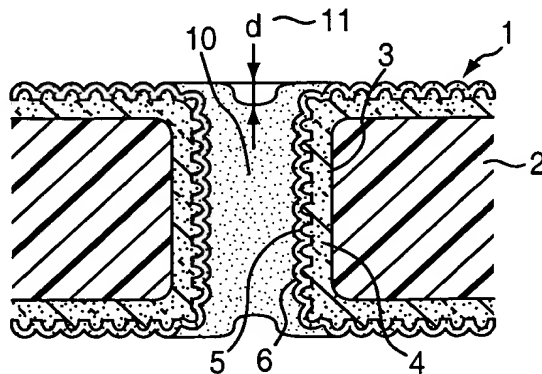




FIG. 7

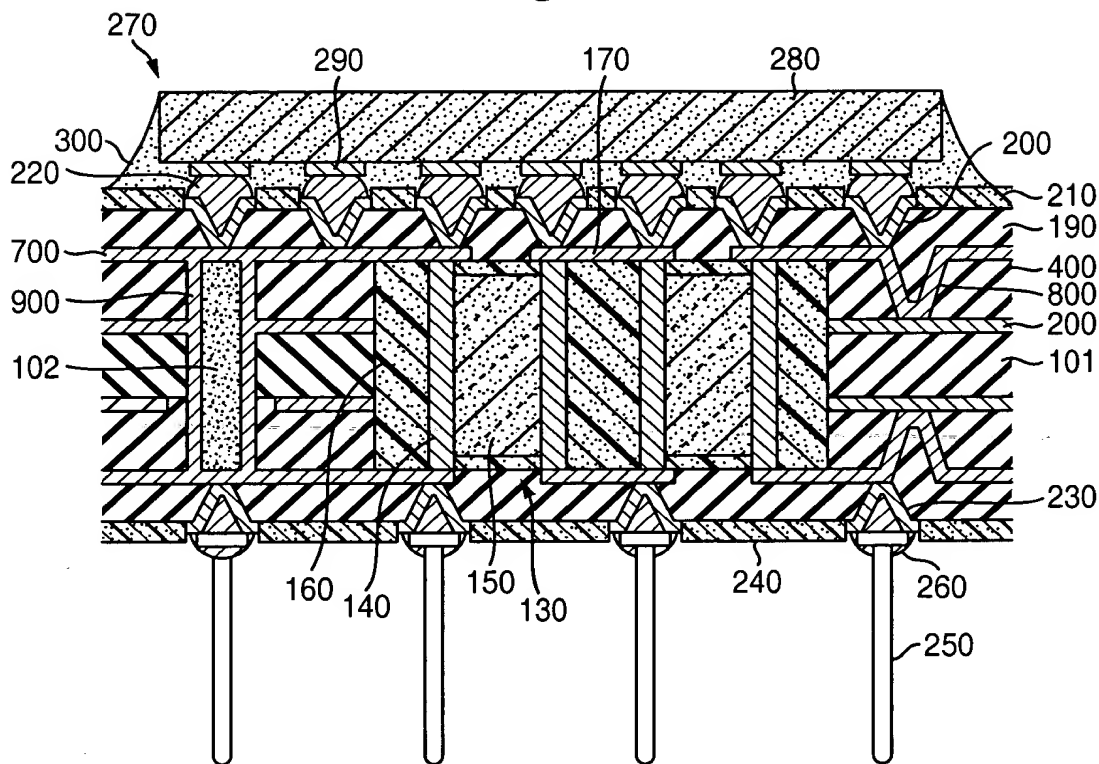


FIG. 8

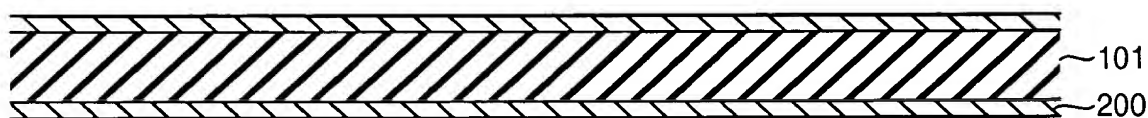


FIG. 9

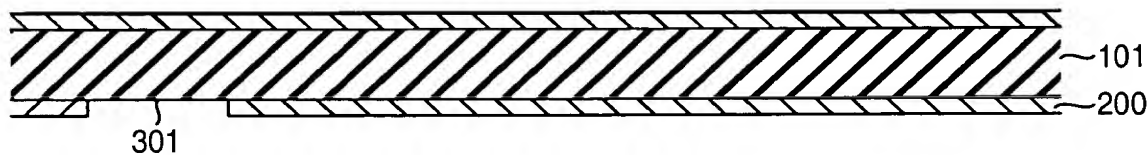




FIG. 10

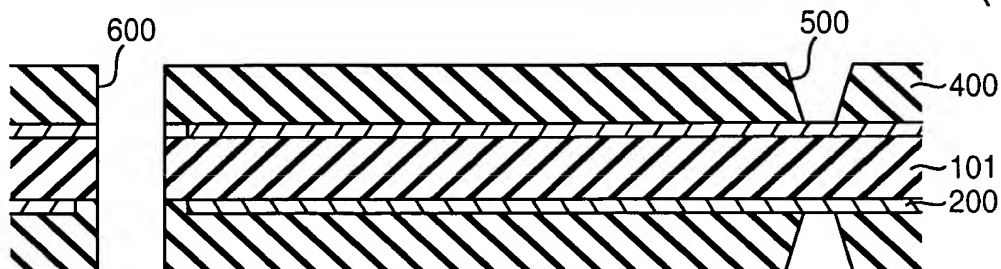


FIG. 11

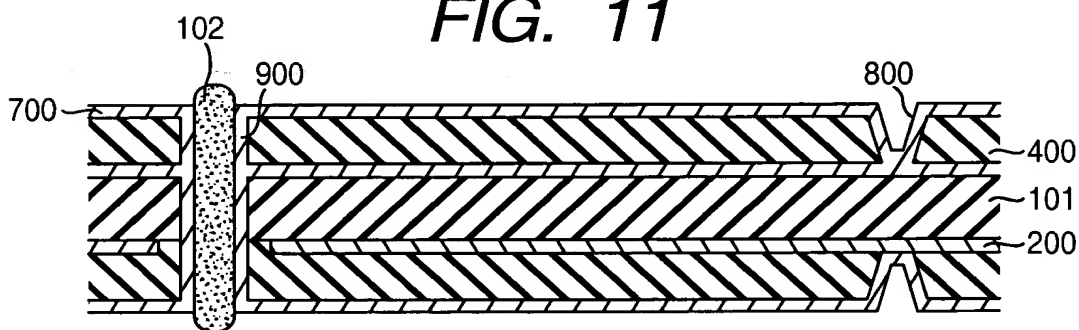


FIG. 12

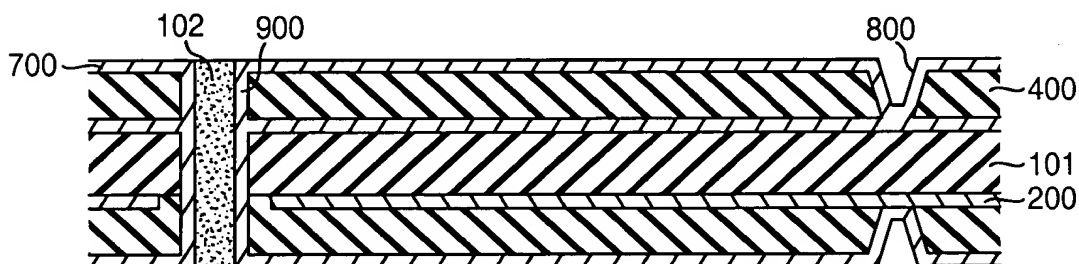


FIG. 13

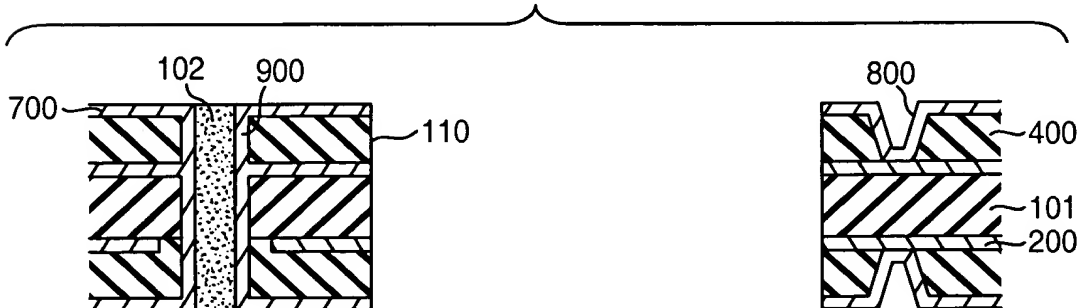




FIG. 14

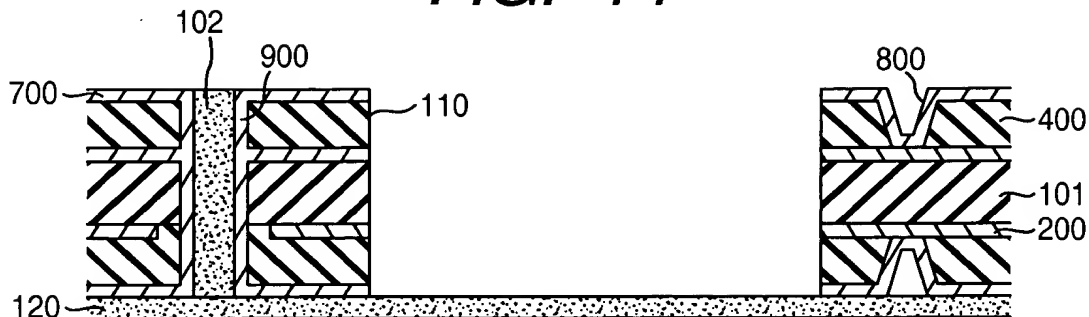


FIG. 15

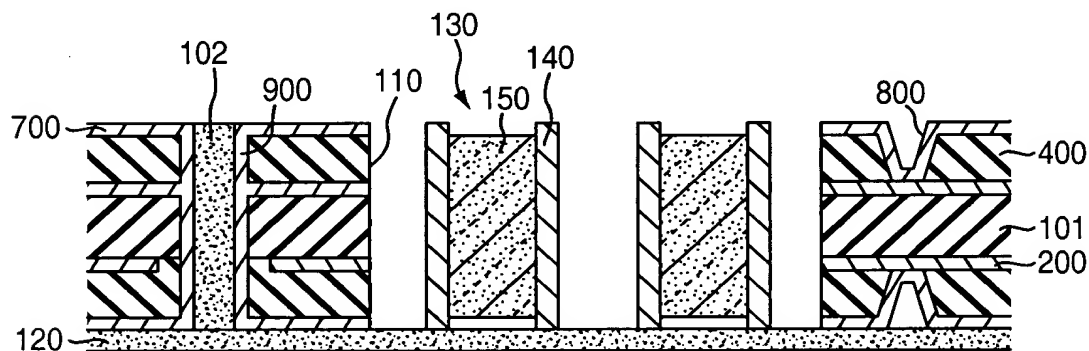


FIG. 16

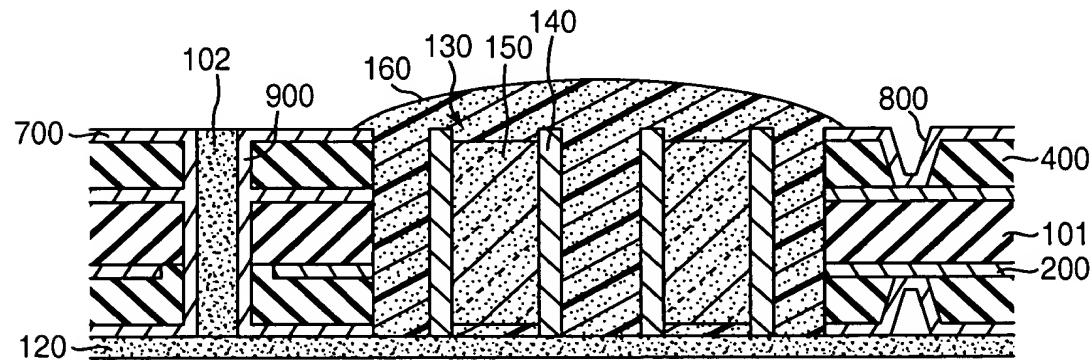




FIG. 17

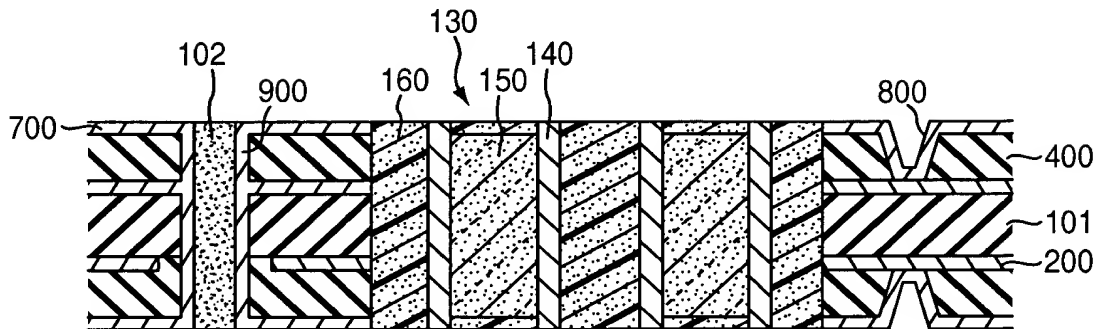


FIG. 18

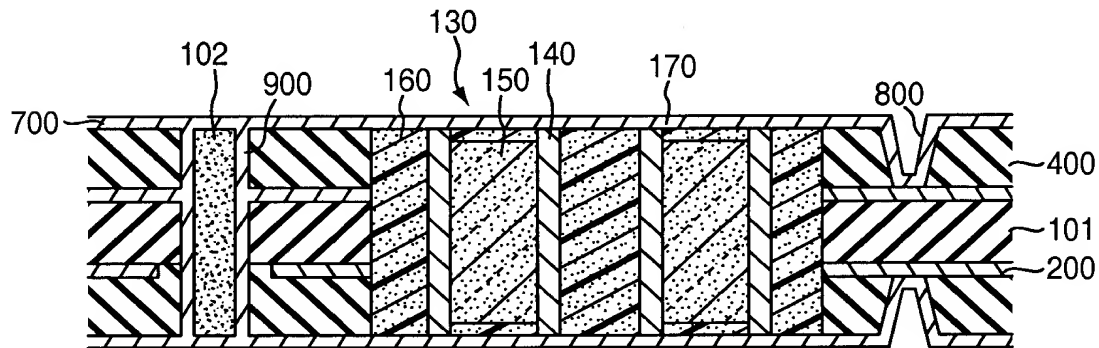
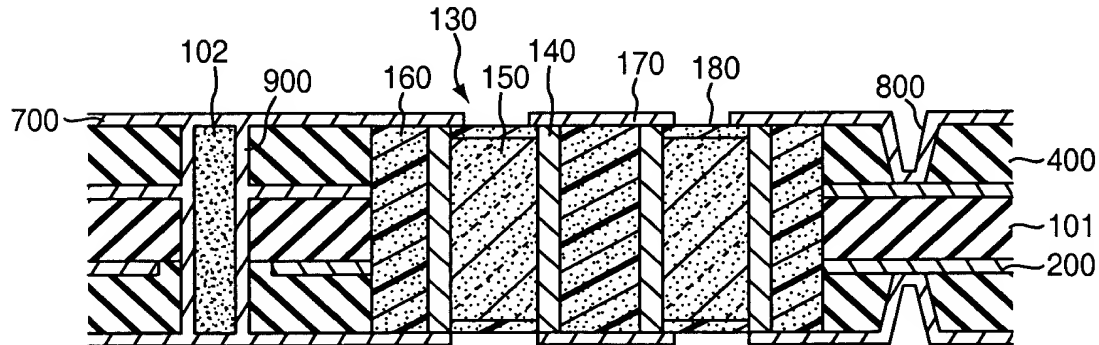


FIG. 19



A detailed cross-sectional view of a semiconductor device. The structure consists of a central vertical column (150) surrounded by a series of horizontal layers. The top layer is labeled 102. Below it is a layer with a wavy interface (900). The central column is composed of several segments: 160, 130, 150, 140, and 170. The bottom of the central column is labeled 200. The central column is flanked by a layer labeled 800. The bottom of the central column is labeled 210. The central column is flanked by a layer labeled 190. The central column is flanked by a layer labeled 400. The central column is flanked by a layer labeled 101. The central column is flanked by a layer labeled 200. The central column is flanked by a layer labeled 230. The central column is flanked by a layer labeled 240.

This cross-sectional view illustrates a semiconductor device with a multi-layered structure. The device features a series of vertical interconnects (250) extending through multiple layers. The layers are labeled with reference numerals: 102, 220, 900, 160, 130, 150, 140, 170, 200, 800, 210, 190, 400, 101, 200, 230, 240, 260, and 250. The structure includes a top layer (102) with a patterned surface (220), a middle section (900) containing vertical interconnects (160, 130, 150, 140, 170), and a bottom section (200, 800, 210) with a patterned surface (190). The device is supported by a substrate (230) and a base layer (240). The vertical interconnects (250) are connected to the top layer (102) and extend through the middle section (900) to the bottom section (200, 800, 210).